

A PROCESS FOR MAKING ADHESIVE BONDED SINTERED PLATES

ABSTRACT

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The present invention is directed to a method of manufacturing of sintered bonded adhesive plates. The present invention comprises the steps of clearing the metal cores, applying thermosetting adhesives, such as phenolic or epoxy adhesives, to the core layer, then applying
10 sintered layers on top of the adhesive layers and bonding said layers at a temperature in the range of 375-475 F, pressure in the range of 25-1000 psi and bonding such structure for at least 30 seconds. The metal core may be fabricated from metals whose melting point is at least 450 F, such as aluminum. The present invention presents a relatively inexpensive way of manufacturing sintered bonded adhesive plates.

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